Development of fast short-circuit protection system for advanced IGBT

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Abstract

IGBTs, one of the representative power devices, have been increased current density by improving the structure. Even now, new structures have been proposed [1]. It indicates that the current density of IGBTs will continue to increase. To improve conduction characteristics for the higher current density, it is necessary to install a fast short-circuit protection system to prevent the IGBT.

Conventional detection method employs non-isolated current detection such as sense IGBT and shunt resistor. This method detects short-circuit condition after 2us or more because the low-pass filter is embedded to remove noise. In addition, shut-down time is also long by fixed high gate resistance to suppress the surge voltage.

The proposed system consists of a small PCB Rogowski coil, integrator, AD converter, digital circuit (FPGA) and digital gate driver. PCB Rogowski coil detects short-circuit current. The measured current signal is fed to FPGA through ADC. When the digital signal exceeds a threshold considered short-circuit, FPGA outputs shut-down signals to a digital gate driver (Fig. 1).

In short-circuit test with the IGBT rated 1200V/50A connected to a DC voltage source of 600 V, the short-circuit detection time is 70ns (Fig. 2). The shut-down time is reduced by controlling the gate resistance at turn-off.



Fig. 1. Diagram of digital gate driver for fast shutdown.

Fig. 2. Short-circuit waveform with proposed system.

References

 M. Tanaka, I. Omura, "IGBT scaling principle toward CMOS compatible wafer processes", Solid-State Electronics Vol.80, pp.118-123, February 2013.